

Package information and functional contact assignments for WQFN

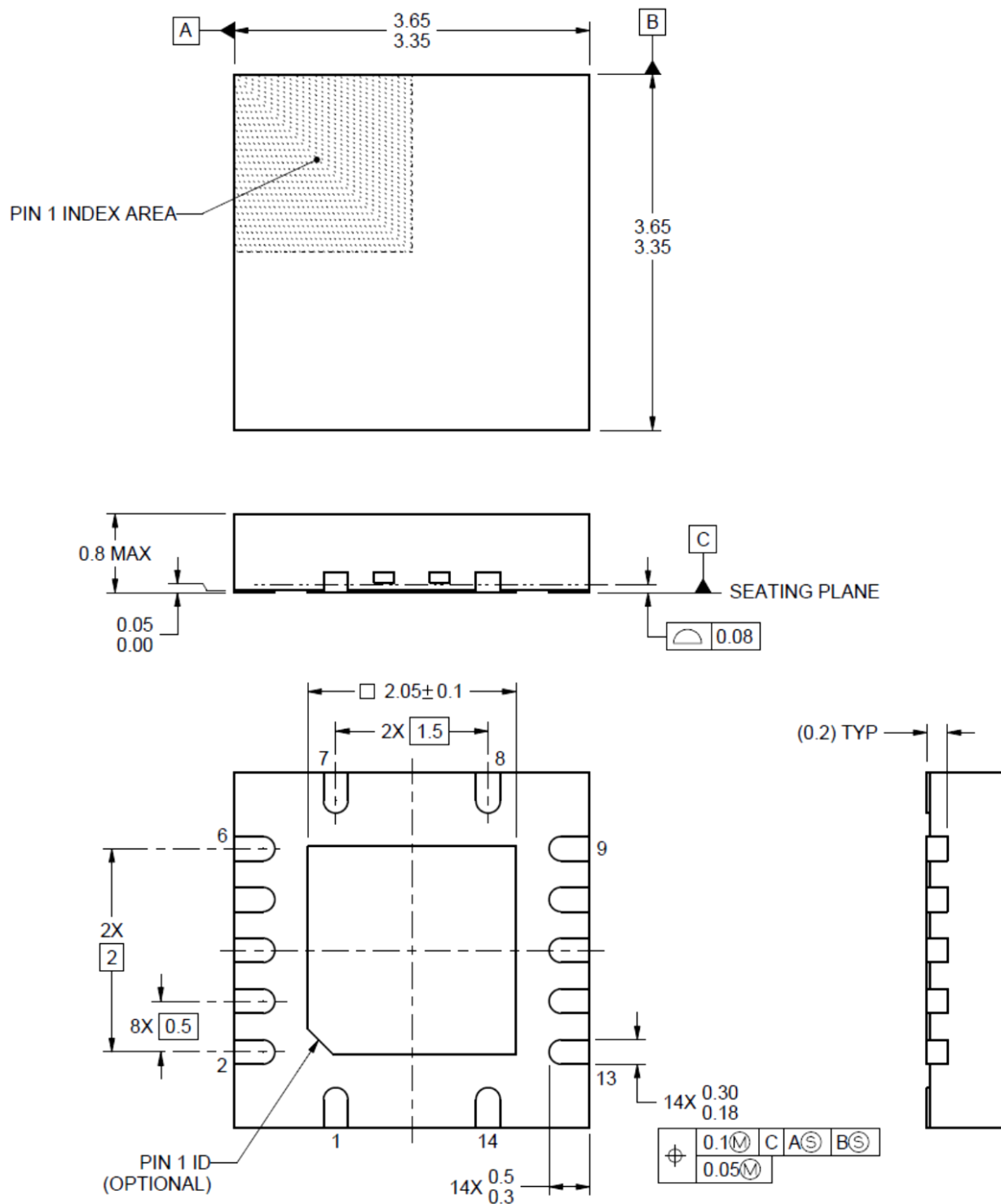


Figure 1. WQFN Package

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerances per ASME Y14.5M.
2. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

Table 1. WQFN functional contact assignments

Pin	Name	Description
2	Ap	Port A, High Speed Positive Signal
3	An	Port A, High Speed Negative Signal
9	Cn	Port C, High Speed Negative Signal
10	Cp	Port C, High Speed Positive Signal
12	Bn	Port B, High Speed Negative Signal
13	Bp	Port B, High Speed Positive Signal

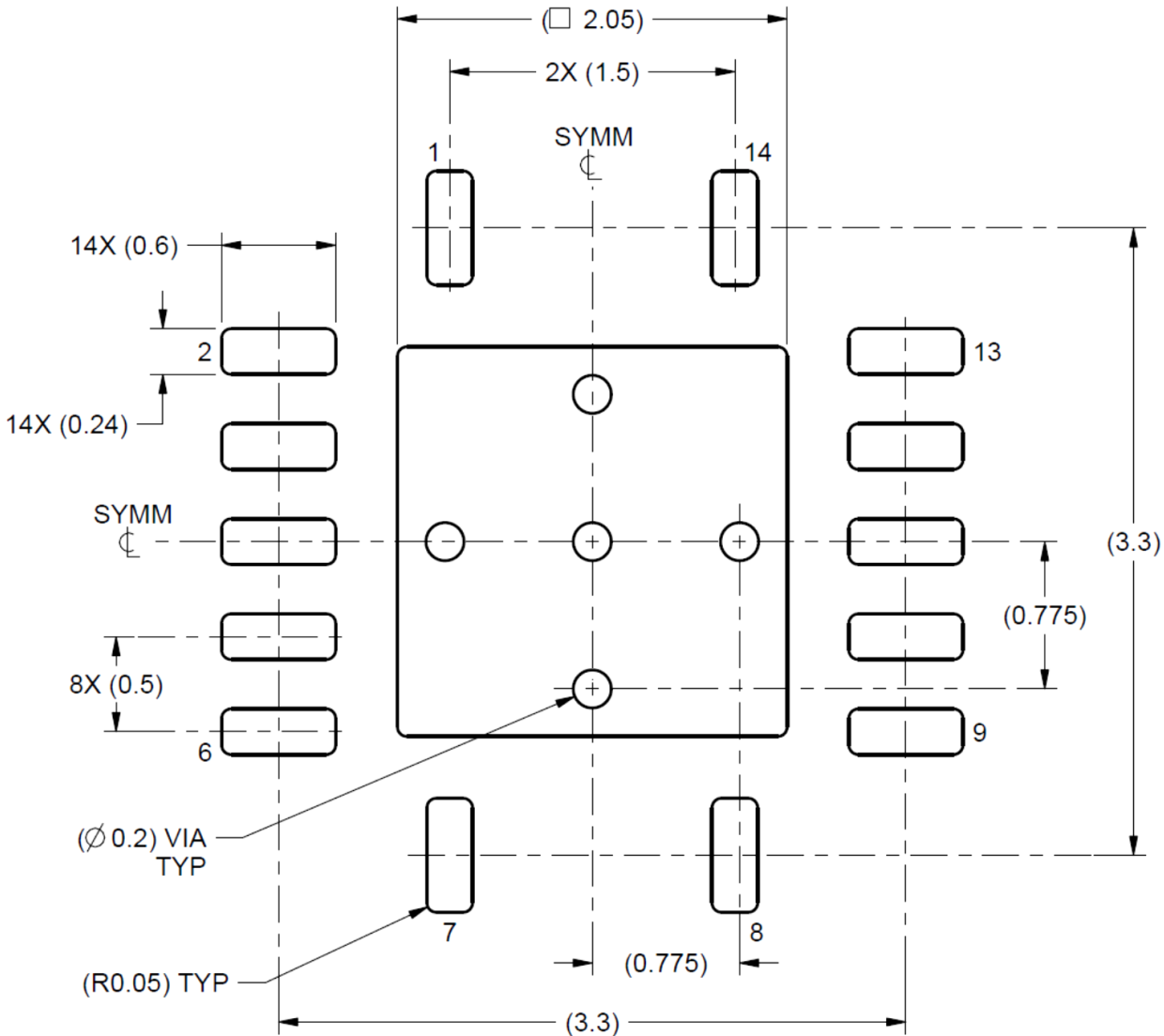


Figure 2. WQFN Land Pattern Example